

FIG. 1

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FORM A METAL SUPPORT LAYER AND A CONDUCTIVE METAL FOIL LAYER JOINED BY AN INORGANIC RELEASE MATERIAL

COAT A SURFACE OF THE CONDUCTIVE METAL FOIL LAYER WITH A HIGH TEMPERATURE ANTI-OXIDANT MATERIAL

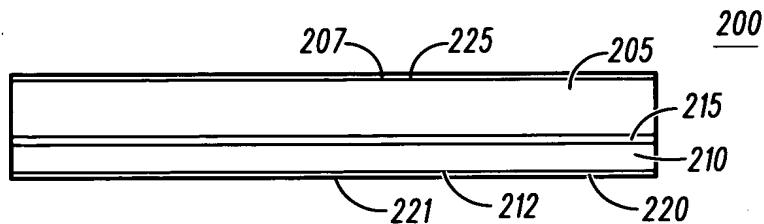


FIG. 2

FORM A CRYSTALLIZED DIELECTRIC OXIDE LAYER ON THE CONDUCTIVE METAL FOIL

FORM AN ELECTRODE LAYER ADJACENT THE CRYSTALLIZED DIELECTRIC OXIDE LAYER ON THE CONDUCTIVE METAL FOIL

LAMINATE PEELABLE CIRCUIT BOARD FOIL TO A LAYER OF A CIRCUIT BOARD

FIG. 3

PEEL AWAY THE METAL SUPPORT LAYER AND OTHER SACRIFICIAL LAYERS

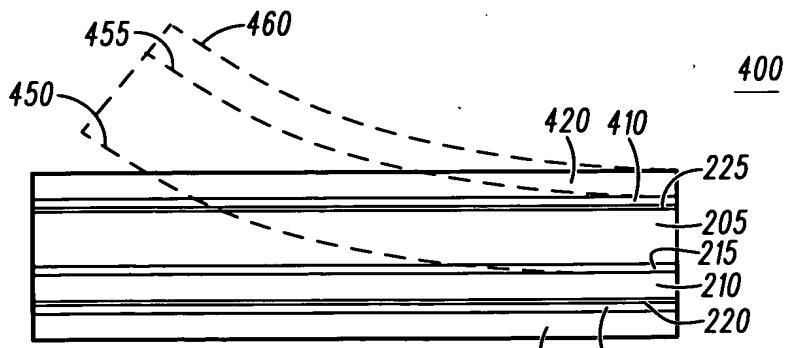


FIG. 4

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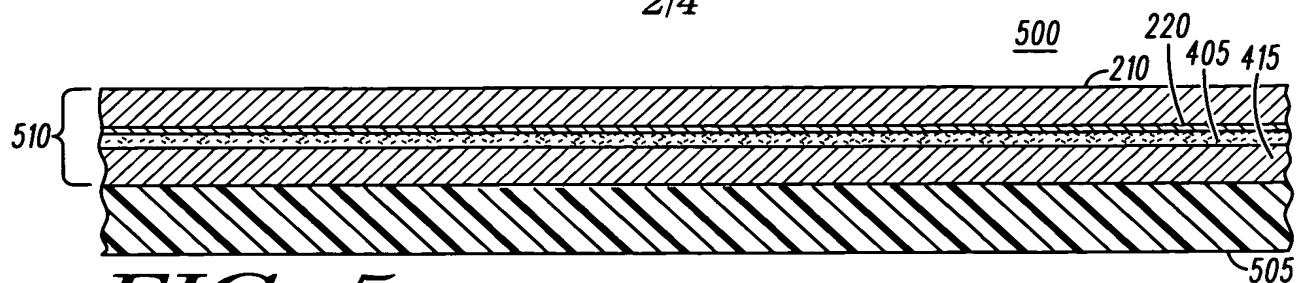


FIG. 5

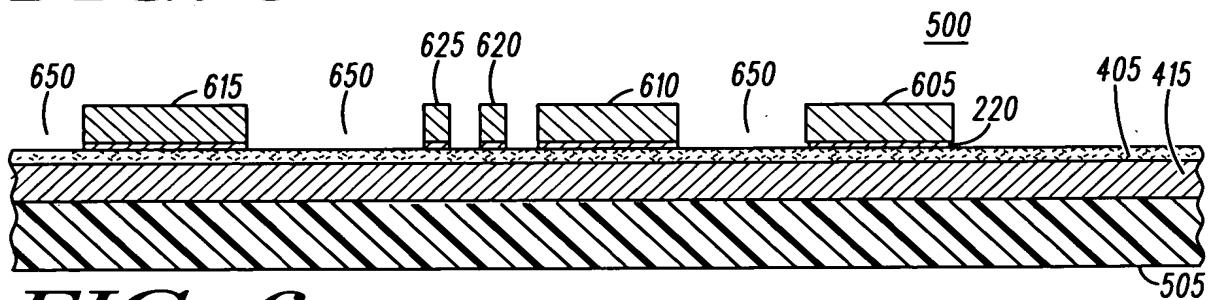


FIG. 6

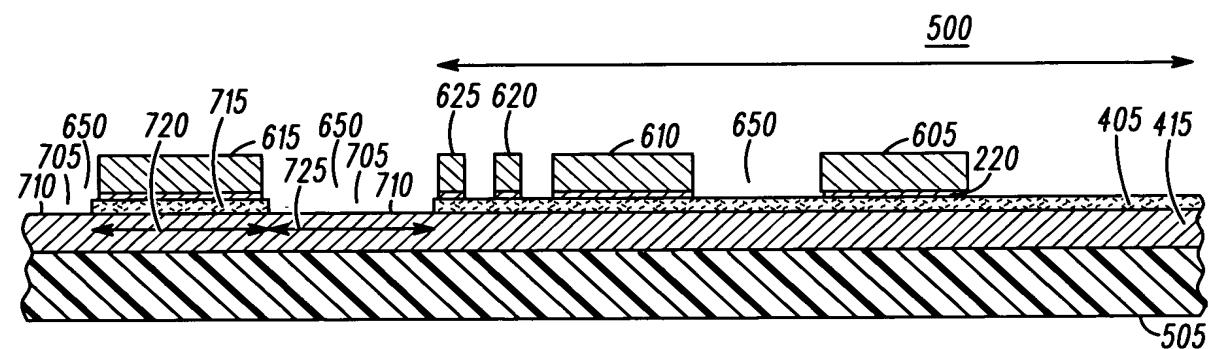


FIG. 7

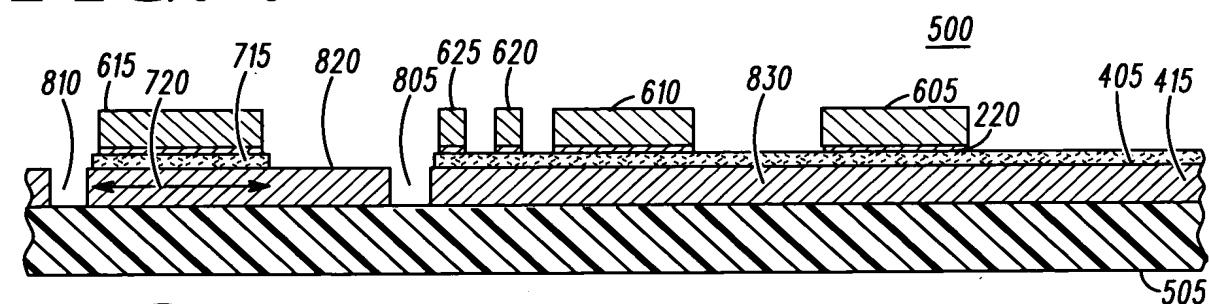


FIG. 8

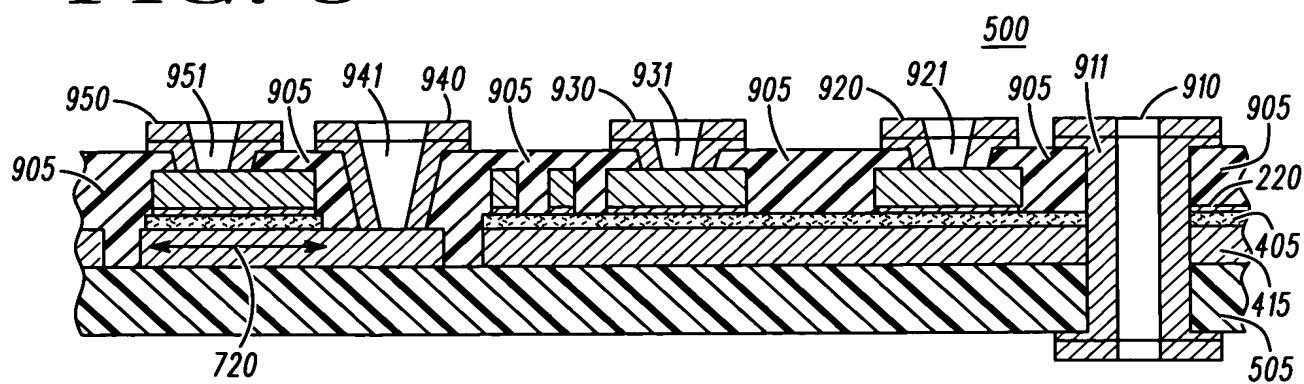


FIG. 9

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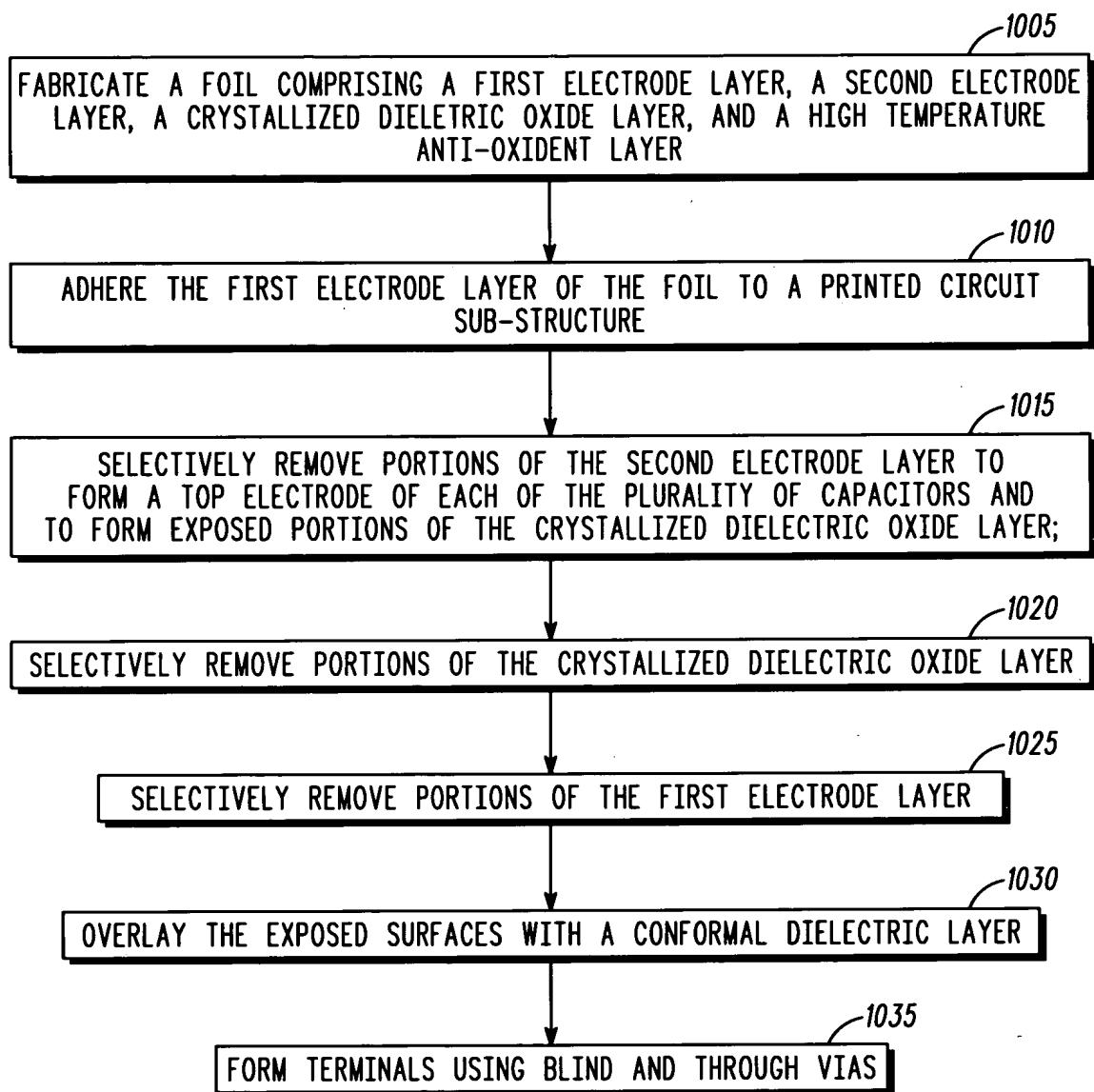


FIG. 10

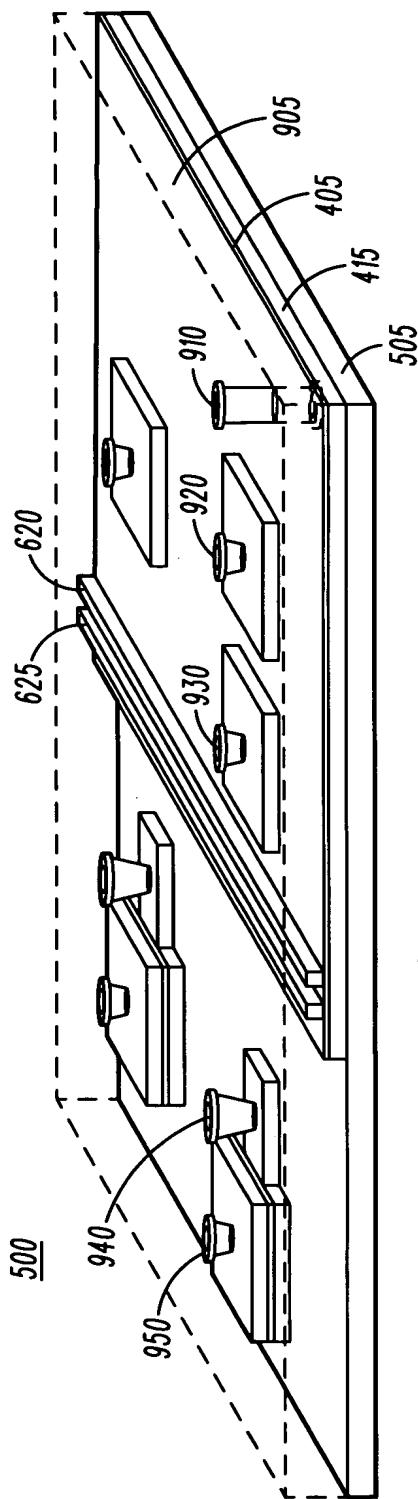


FIG. 11

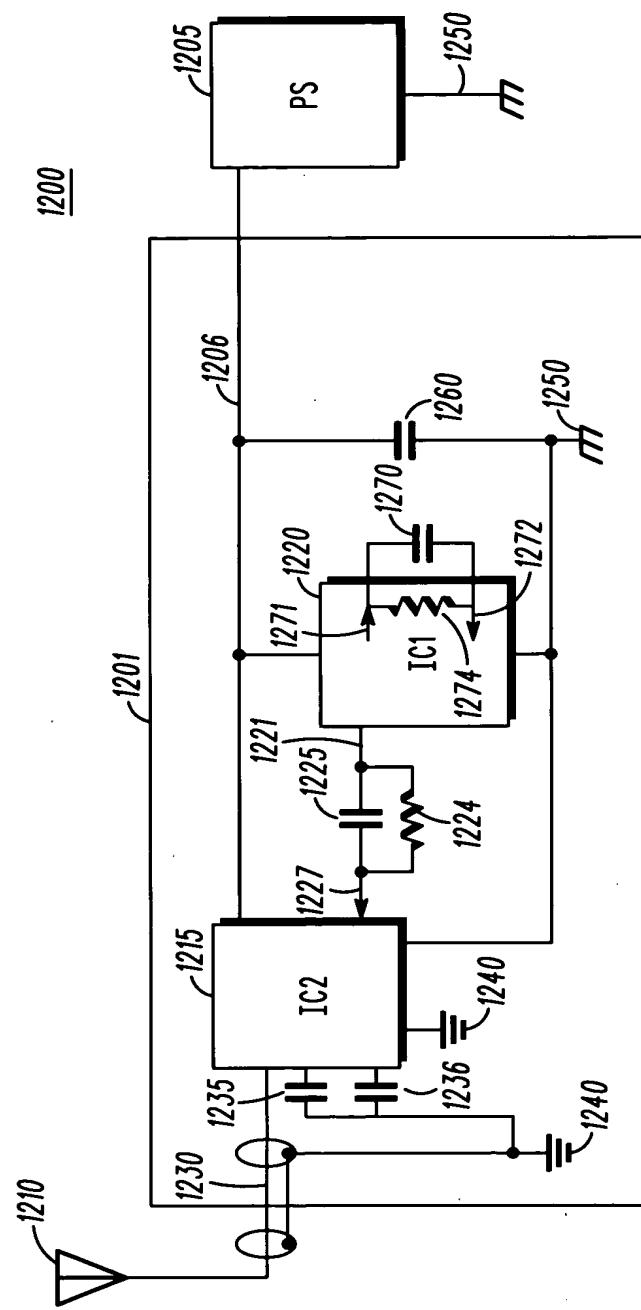


FIG. 12